

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7281	(@ad<"20010611") and (chip or die) and (((substrate or sheet or film or frame or pad or paddle) and (mold or molding)) same (force or forcibly or press or lift or push))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:27
L2	3988	(@ad<"20010611") and (chip or die) and (((substrate or sheet or film or frame or pad or paddle) and (mold or molding)) with(force or forcibly or press or lift or push))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:25
L3	3988	(@ad<"20010611") and (chip or die) and (((substrate or sheet or film or frame or pad or paddle) and (mold or molding)) with (force or forcibly or press or lift or push))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 10:47
L4	716	L3 and (encapsulate or encapsulant or epoxy) and (excision or cut or saw or snip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 10:49
L5	5	L3 and (die adj (down or up))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 10:49
L6	9	L3 and ((die near (up or down)) with ((force or forcibly or press or lift or push)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:26
L7	117	((die near (up or down)) and pin\$1) with ((force or forcibly or press or lift or push)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:27
L8	14	L7 and (@ad<"20010611") and (chip or die) and (mold or molding or encapsulate or encapsulant or epoxy or plastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:27

L9	15	L7 and (@ad<"20010611") and (chip or die) and (mold or molding or encapsulate or encapsulant or epoxy or plastic or resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:28
----	----	--	---	----	-----	------------------